PCN Number:	20160412000	PCN Date:	4/14/2016
Title:	Qualification of new Assembly/Test site (TI Clark) for the TPS626751YFD		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	7/14/2016	Estimated Sample Availability:	Provided upon Request

Change Type:

☒	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☒	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification TI Clark as a new Assembly site for the TPS626751YFD device. There are no construction differences between devices built at the 2 sites

Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

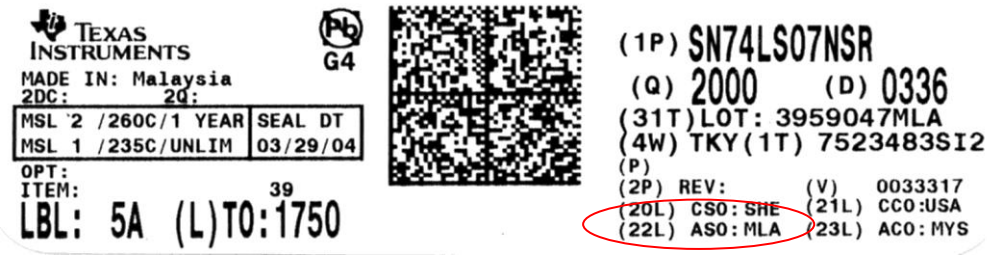
Anticipated impact on Material Declaration

☒	No Impact to the Material Declaration	☐	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website.

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City
ASEK	ASF	TWN	Kaohsiung
TI Clark	**QAB**	**PHL**	**Angeles City**

Sample product shipping label (not actual product label)



Topside Device marking:
Assembly site code for ASF= 7
Assembly site code for QAB = I

Product Affected

TPS626751YFDR	TPS626751YFDT

TEXAS INSTRUMENTS

TI Information
Selective Disclosure

Qualification Report

Offload TPS6267xYFD from ASEK to Clark Bump/Probe/AT
Approve Date 30-Mar-2016

Product Attributes

Attributes	QBS Product Reference: TPS62674YFD	QBS Process Reference: BQ24721RHB	QBS Process Reference: BQ24730RGF	QBS Package Reference: PLM3638A3CYFDR
Assembly Site	ASEK	MLA	MLA	CLARK AT
Package Family	WCSP	QFN	QFN	WCSP
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	DMOS 5	DMOS 5	DMOS 5	RFAB
Wafer Process	LBC7	LBC7	LBC7	LBC8LV

- QBS: Qual By Similarity
- Qual Devices qualified at LEVEL1-260C: TPS62675YFD, TPS62671YFD, TPS626751YFD

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	QBS Product Reference: TPS62674YFD	QBS Process Reference: BQ24721RHB	QBS Process Reference: BQ24730RGF	QBS Package Reference: PLM3638A3CYFDR
AC	Autoclave 121C	96 Hours	-	3/231/0	-	-
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	3/231/0
HBM	ESD - HBM	3000 V	1/3/0	-	-	-
CDM	ESD - CDM	1000 V	1/3/0	-	-	3/9/0
HTOL	Life Test, 125C	500 Hours	-	-	-	3/231/0
HTOL	Life Test, 150C	300 Hours	-	-	-	3/231/0
HTOL	Life Test, 155C	240 Hours	-	-	3/231/0	-
HTSL	High-Temp Storage, 170C	420 Hours	-	3/231/0	-	2/154/0
LU	Latch-up	(per JESD78)	1/6/0	3/15/0	-	3/18/0
SBS	Solder Ball Shear	--	-	-	-	3/15/0
TC	Temperature Cycle, -55/125C	700 Cycles	-	-	-	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	-	-
TS	Thermal Shock, -65/150C	500 Cycles	-	3/231/0	-	-
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	-	-	3/231/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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USA	PCNAmericasContact@list.ti.com
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